

METHODS OF APPLYING SUBSTANCE TO INTEGRATED CIRCUIT DIE AND
LEAD FRAMES TO IMPROVE ADHESION TO MOLD COMPOUND, APPARATUS
AND DEVICES

ABSTRACT

A process of making an integrated circuit. The process has steps of providing an adhesion promoting substance to an applicator device operable to atomize the adhesion promoting substance, establishing a potential difference between the applicator device and the integrated circuit, and atomizing the adhesion promoting substance near the integrated circuit so that the potential difference attracts the adhesion promoting substance to the integrated circuit thereby depositing the adhesion promoting substance thereon. In a product aspect an integrated circuit has pins, a layer of atomized adhesion promoting substance deposited on the pins, and a package material molded onto the pins and the adhesion promoting substance. Other devices, systems and methods are also disclosed.

